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### FDS4672A

### 40V N-Channel PowerTrench® MOSFET

### **General Description**

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low  $R_{\text{DS}(\text{ON})}$  and fast switching speed.

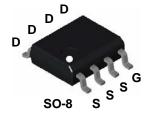
### **Applications**

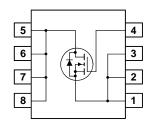
DC/DC converter

### **Features**

- 11 A, 40 V.  $R_{DS(ON)} = 13 \text{ m}\Omega$  @  $V_{GS} = 4.5 \text{ V}$
- $\bullet \;\; \mbox{High performance trench technology for extremely} \;\; \mbox{low} \;\; \mbox{R}_{\mbox{\scriptsize DS(ON)}}$
- Low gate charge (35 nC typical)
- High power and current handling capability
- RoHS Compliant







### Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter		Ratings	
V <sub>DSS</sub>	Drain-Source Voltage		40	Units
V <sub>GSS</sub>	Gate-Source Voltage		±12	V
I <sub>D</sub>	Drain Current - Continuous	(Note 1a)	11	А
	– Pulsed		50	
E <sub>AS</sub>	Single Pulse Avalanche Energy	(Note 3)	181	mJ
$P_D$	Power Dissipation for Single Operation	(Note 1a)	2.5	W
		(Note 1b)	1.4	
		(Note 1c)	1.2	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperat	ure Range	-55 to +175	°C

### **Thermal Characteristics**

R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	(Note 1a)	50	°C/W
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	(Note 1)	25	°C/W

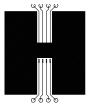
**Package Marking and Ordering Information** 

Device Marking	Device	Reel Size	Tape width	Quantity
FDS4672A	FDS4672A	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics		l		l	I
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40			V
<u>ΔBV<sub>DSS</sub></u> ΔΤ <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$ , Referenced to 25°C		37		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 32 \text{ V},  V_{GS} = 0 \text{ V}$			1	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage, Forward	V <sub>GS</sub> = 12 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage, Reverse	V <sub>GS</sub> = -12 V V <sub>DS</sub> = 0 V			-100	nA
On Char	acteristics (Note 2)					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.8	1.2	2.0	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, Referenced to 25°C		-4		mV/°C
R <sub>DS(on)</sub>	Static Drain–Source On–Resistance	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 11 A V <sub>GS</sub> =4.5 V, I <sub>D</sub> =11A, T <sub>J</sub> =125°C		10 15	13 21	mΩ
I <sub>D(on)</sub>	On-State Drain Current	$V_{GS} = 4.5 \text{ V}, V_{DS} = 5 \text{ V}$	50			Α
g <sub>FS</sub>	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 11 \text{ A}$		65		S
Dvnamio	Characteristics		•	•	•	
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 20 \text{ V},  V_{GS} = 0 \text{ V},$		4766		pF
Coss	Output Capacitance	f = 1.0 MHz		346		pF
C <sub>rss</sub>	Reverse Transfer Capacitance	7		155		pF
Switchin	g Characteristics (Note 2)		•		•	•
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 20 \text{ V},  I_D = 1 \text{ A},$		17	31	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 4.5 \text{ V}, R_{GEN} = 6 \Omega$		9	18	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			43	68	ns
t <sub>f</sub>	Turn-Off Fall Time	7		14	25	ns
Q <sub>g</sub>	Total Gate Charge	$V_{DS} = 20 \text{ V}, I_{D} = 11 \text{ A},$		35	49	nC
$Q_{gs}$	Gate-Source Charge	$V_{GS} = 4.5 \text{ V}$		7.8		nC
$Q_{gd}$	Gate-Drain Charge	<u> </u>		8.8		nC
Drain-Se	ource Diode Characteristics	and Maximum Ratings				
I <sub>s</sub>	Maximum Continuous Drain-Source				2.1	Α
$V_{SD}$	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V},  I_S = 2.1 \text{ A}  \text{(Note 2)}$		0.7	1.2	V
	·	•	· · · · · · · · · · · · · · · · · · ·			

### Notes:

<sup>1.</sup>  $R_{\text{BJA}}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\text{BJC}}$  is guaranteed by design while  $R_{\text{BCA}}$  is determined by the user's board design.



a) 50°C/W when mounted on a 1in² pad of 2 oz copper



b) 105°C/W when mounted on a .04 in<sup>2</sup> pad of 2 oz copper



c) 125°C/W when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

**2.** Pulse Test: Pulse Width <  $300\mu$ s, Duty Cycle < 2.0%

3.Starting  $T_J = 25^{\circ}C$ , L = 3mH,  $I_D = 11A$ ,  $V_{DD} = 40V$ ,  $V_{GS} = 10V$ 

### **Typical Characteristics**

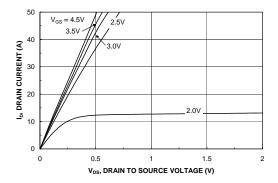


Figure 1. On-Region Characteristics.

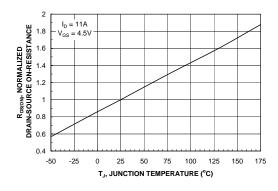


Figure 3. On-Resistance Variation with Temperature.

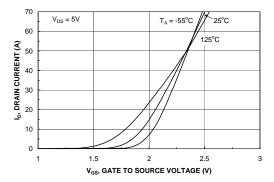


Figure 5. Transfer Characteristics.

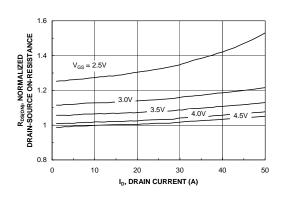


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

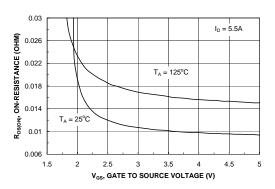


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

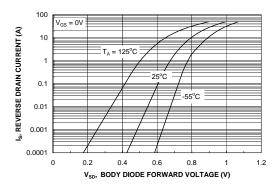
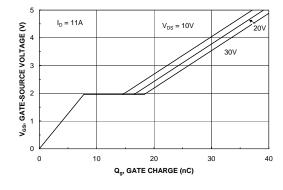


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

### **Typical Characteristics**



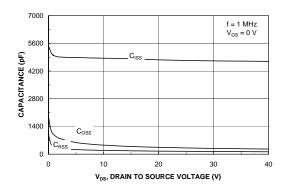


Figure 7. Gate Charge Characteristics.

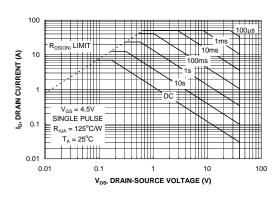


Figure 8. Capacitance Characteristics.

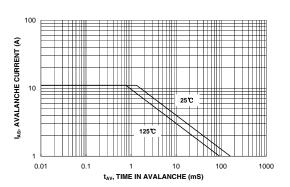


Figure 9. Maximum Safe Operating Area.



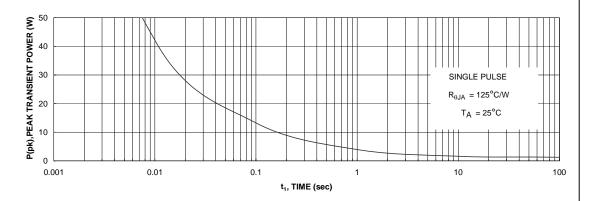


Figure 11 Single Pulse Maximum Power Dissipation.

## **Typical Characteristics**

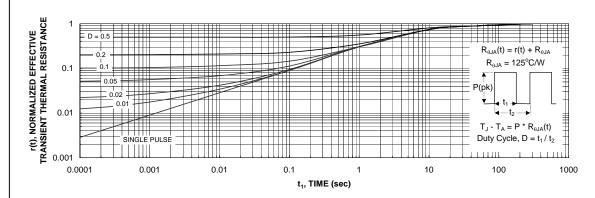


Figure 12. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c.

Transient thermal response will change depending on the circuit board design.

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UniFET™ VCX™ Wire™

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